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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 09/148,723  
Filing Date .... September 3, 1998  
Inventor .... Warren M. Farnworth et al.  
Assignee .... Micron Technology, Inc.  
Group Art Unit .... 3729  
Examiner .... D. Tugbang  
Attorney's Docket No. .... MI22-981  
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

References- - See attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the references listed on the attached Form PTO-1449. No admission is made regarding whether the submitted references are prior art.

Citation of these references is respectfully requested.

Respectfully submitted,

Date:

Handwritten: March 26, 2002

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